# Nch 650V 11A Power MOSFET

V <sub>DSS</sub>	650V
R <sub>DS(on)</sub> (Max.)	0.40Ω
I <sub>D</sub>	±11A
P <sub>D</sub>	124W

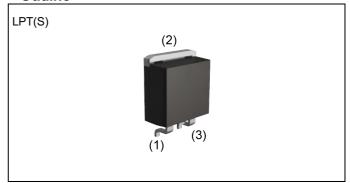
### Features

- 1) Low on-resistance
- 2) Ultra fast switching speed
- 3) Parallel use is easy
- 4) Pb-free plating; RoHS compliant

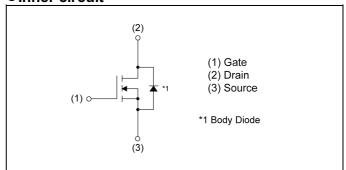
# Application

Switching

### Outline



# •Inner circuit



Packaging specifications

Packing	Embossed Tape
Packing code	TL
Marking	R6511KNJ
Basic ordering unit (pcs)	1000

# ullet Absolute maximum ratings (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V <sub>DSS</sub>	650	V
Continuous drain current (T <sub>c</sub> = 25°C)		I <sub>D</sub> *1	±11	Α
Pulsed drain current		I <sub>DP</sub> *2	±33	Α
Coto Course vallesse	static	V	±20	V
Gate - Source voltage	AC(f>1Hz)	$V_{GSS}$	±30	V
Avalanche current, single pulse		I <sub>AS</sub>	1.8	А
Avalanche energy, single pulse		E <sub>AS</sub> *3	223	mJ
Power dissipation (T <sub>c</sub> = 25°C)	P <sub>D</sub>	124	W	
Junction temperature	T <sub>j</sub>	150	°C	
Operating junction and storage tempera	ature range	T <sub>stg</sub>	-55 to +150	°C

### ●Thermal resistance

Downwortow	Cymah al	Values			1.1:4
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *4	-	-	1.0	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub> *5	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Parameter	Cumb al	Conditions	Values			Unit
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	650	-	1	V
		$V_{DS} = 650V, V_{GS} = 0V$				
Zero gate voltage drain current	I <sub>DSS</sub>	$T_j = 25^{\circ}C$	-	-	100	μΑ
aram canoni		T <sub>j</sub> = 125°C	-	-	1000	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 320 \mu A$	3	-	5	٧
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 3.8A				
Static drain - source on - state resistance	R <sub>DS(on)</sub> *6	$T_j = 25^{\circ}C$	-	0.36	0.40	Ω
		T <sub>j</sub> = 125°C	-	-	-	
Gate resistance	$R_{G}$	f = 1MHz, open drain	-	2.4	-	Ω

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davamatar	Cymah al	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	UHIL	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	760	-		
Output capacitance C		V <sub>DS</sub> = 25V	-	710	-	pF	
Reverse transfer capacitance C <sub>rss</sub>		f = 1MHz	-	30	-		
Turn - on delay time	t <sub>d(on)</sub> *6	$V_{DD} \simeq 300V$ , $V_{GS} = 10V$	-	22	-		
Rise time	t <sub>r</sub> *6	I <sub>D</sub> = 5.5A	-	20	-		
Turn - off delay time	t <sub>d(off)</sub> *6	$R_L \simeq 54.9\Omega$	-	45	-	ns	
Fall time	t <sub>f</sub> *6	$R_G = 10\Omega$	-	15	-		

# ● Gate charge characteristics (T<sub>a</sub> = 25°C)

Darameter	Cymahal	Conditions	Values			Lloit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	$Q_g^{*6}$	V <sub>DD</sub> ≈ 300V	-	22	-	
Gate - Source charge	Q <sub>gs</sub> *6	I <sub>D</sub> = 11A	-	6	1	nC
Gate - Drain charge	${\sf Q_{gd}}^{*6}$	V <sub>GS</sub> = 10V	-	10	-	
Gate plateau voltage	V <sub>(plateau)</sub>	V <sub>DD</sub> ≈ 300V, I <sub>D</sub> = 11A	-	6.7	-	V

<sup>\*1</sup> Limited only by maximum channel temperature allowed.

<sup>\*2</sup> Pw ≤ 10µs, Duty cycle ≤ 1%

<sup>\*3</sup> L $\doteqdot$ 100mH, V<sub>DD</sub>=50V, R<sub>G</sub>=25 $\Omega$ , STARTING T<sub>i</sub>=25 $^{\circ}$ C

<sup>\*4</sup> T<sub>C</sub>=25°C

<sup>\*5</sup> Mounted on an epoxy PCB FR4 (25mm x 27mm x 0.8mm)

<sup>\*6</sup> Pulsed

# ●Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	UTIIL	
Source current	I <sub>S</sub> *1	· T <sub>C</sub> = 25°C	1	-	11	Α	
Pulsed source current	l <sub>SP</sub> *2	1C - 23 C	1	-	33	Α	
Source-Drain voltage	V <sub>SD</sub> *6	$V_{GS} = 0V, I_{S} = 11A$	-	-	1.5	V	
Reverse recovery time	t <sub>rr</sub> *6		-	390	-	ns	
Reverse recovery charge	Q <sub>rr</sub> *6	I <sub>S</sub> = 11A di/dt = 100A/μs	-	4.5	-	μC	
Peak reverse recovery current	<sub>rr</sub> *6		-	23	-	Α	

Fig.1 Power Dissipation Derating Curve

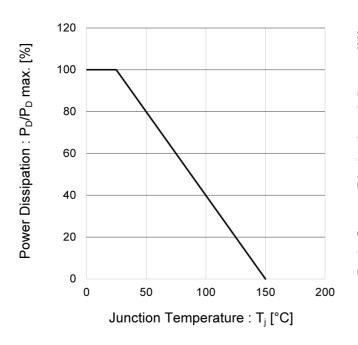


Fig.2 Drain Current Derating Curve

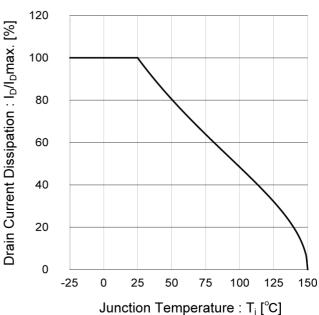


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

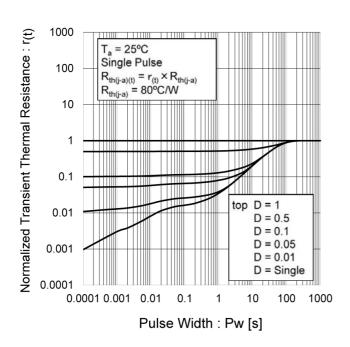
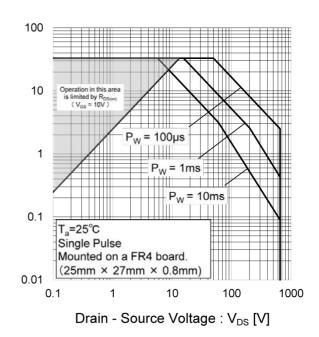


Fig.4 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Fig.5 Avalanche Energy Derating
Curve vs. Junction Temperature

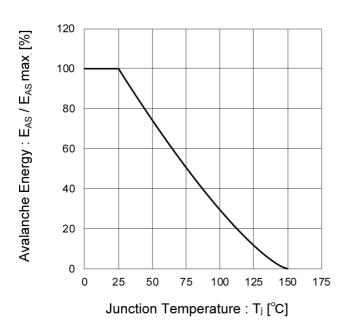


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

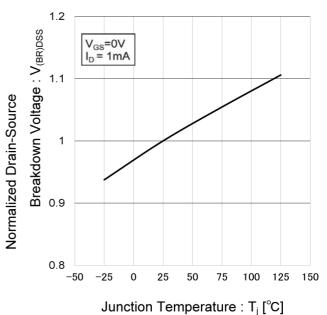


Fig.7 Typical Output Characteristics(I)

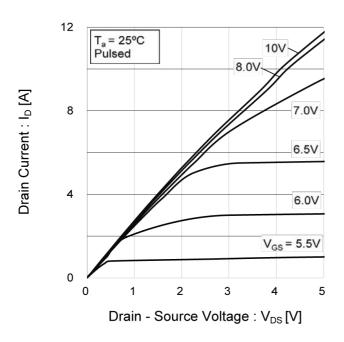
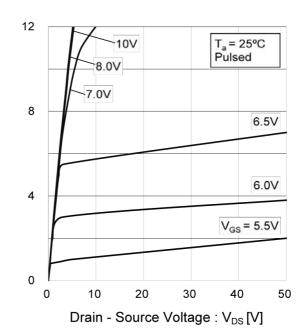


Fig.8 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

Fig.9 Typical Transfer Characteristics

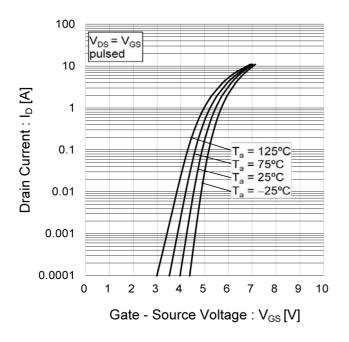


Fig.10 Normalized Gate Threshold .

Voltage vs Junction Temperature

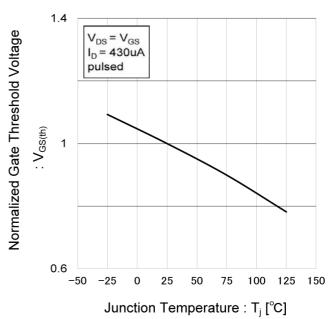


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

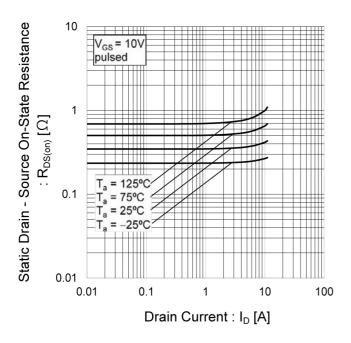


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

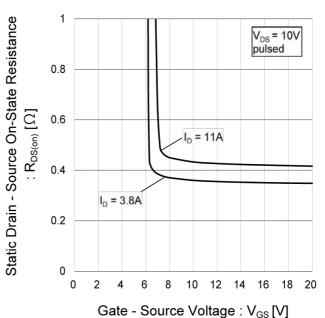


Fig.13 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

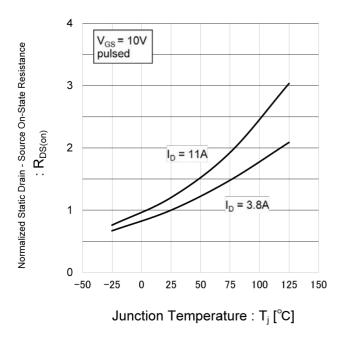
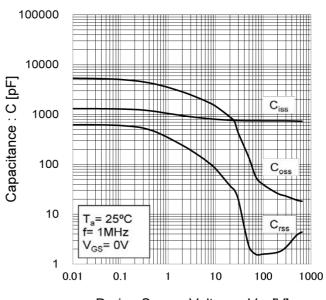


Fig.14 Typical Capacitance vs.

Drain - Source Voltage



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.15 Switching Characteristics

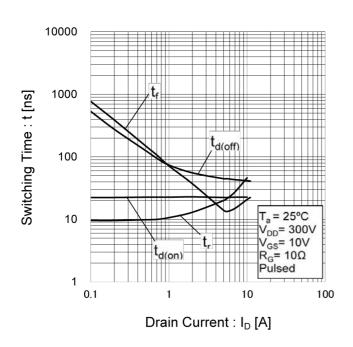
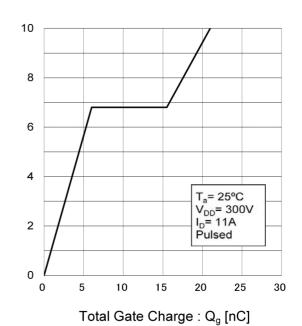


Fig.16 Typical Gate Charge



Gate - Source Voltage : V<sub>GS</sub> [V]

Fig.17 Source Current vs. Source - Drain Voltage

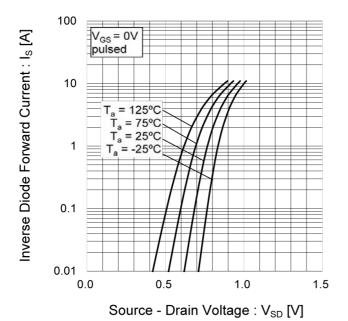
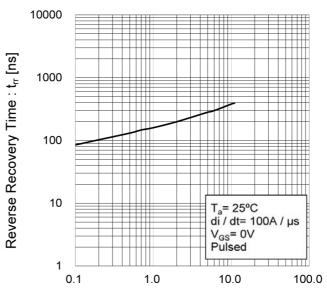


Fig.18 Reverse Recovery Time vs.
Inverse Diode Forward Current



Inve

Inverse Diode Forward Current: I<sub>S</sub> [A]

### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

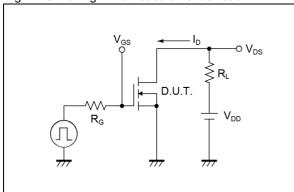


Fig.2-1 Gate Charge Measurement Circuit

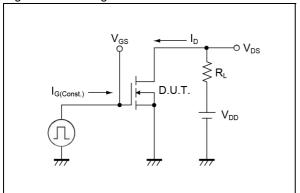


Fig.3-1 Avalanche Measurement Circuit

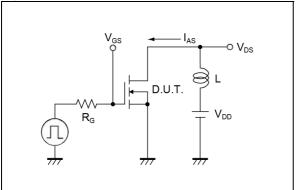


Fig.4-1 trr Measurement Circuit

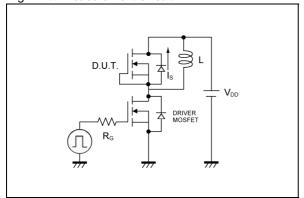


Fig.1-2 Switching Waveforms

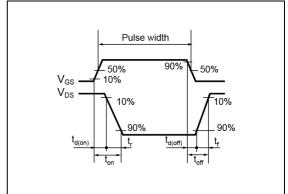


Fig.2-2 Gate Charge Waveform

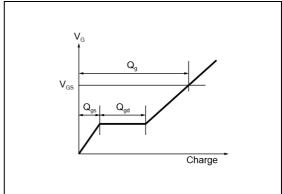


Fig.3-2 Avalanche Waveform

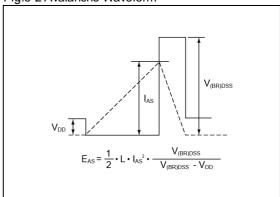
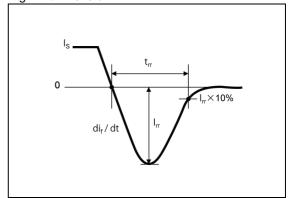
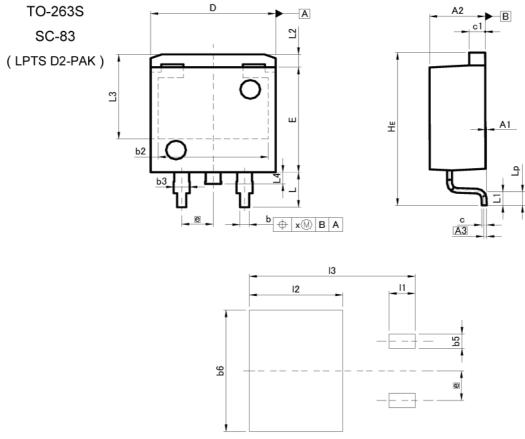


Fig.4-2 trr Waveform



# Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES		
DIM	MIN	MAX	MIN	MAX		
A1	0.00	0.30	0.000	0.012		
A2	4.30	4.70	0.169	0.185		
A3	0.	25	0.0	10		
b	0.68	0.98	0.027	0.039		
b2		90		50		
b3	1.14	1.44	0.045	0.057		
С	0.30	0.60	0.012	0.024		
c1	1.10	1.50	0.043	0.059		
D	9.80	10.40	0.386	0.409		
E	8.80	9.20	0.346	0.362		
е	2.	54	0.1	00		
HE	12.80	13.40	0.504	0.528		
L	2.70	3.30	0.106	0.130		
L1	1.	20	0.047			
L2	1.	10	0.043			
L3	7.	.25 0.285		7.25		85
L4	1.	00	0.0	39		
Lp	0.90	1.50	0.035	0.059		
X	_	0.25	· -	0.010		

 DIM
 MILIMETERS
 INCHES

 MIN
 MAX
 MIN
 MAX

 b5
 1.23
 0.049

 b6
 10.40
 0.409

 I1
 2.10
 0.083

 I2
 7.55
 0.297

 I3
 13.40
 0.528

Dimension in mm/inches



# **Notice**

#### **Precaution on using ROHM Products**

Our Products are designed and manufactured for application in ordinary electronic equipments (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JÁPAN	USA	EU	CHINA
CLASSⅢ	ОГАССШ	CLASS II b	CLASSⅢ
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSIII

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
  - [a] Installation of protection circuits or other protective devices to improve system safety
  - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### **Precaution for Mounting / Circuit board design**

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

#### **Precaution for Product Label**

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

#### **Precaution for Disposition**

When disposing Products please dispose them properly using an authorized industry waste company.

#### **Precaution for Foreign Exchange and Foreign Trade act**

Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

#### **Precaution Regarding Intellectual Property Rights**

- 1. All information and data including but not limited to application example contained in this document is for reference only. ROHM does not warrant that foregoing information or data will not infringe any intellectual property rights or any other rights of any third party regarding such information or data.
- 2. ROHM shall not have any obligations where the claims, actions or demands arising from the combination of the Products with other articles such as components, circuits, systems or external equipment (including software).
- 3. No license, expressly or implied, is granted hereby under any intellectual property rights or other rights of ROHM or any third parties with respect to the Products or the information contained in this document. Provided, however, that ROHM will not assert its intellectual property rights or other rights against you or your customers to the extent necessary to manufacture or sell products containing the Products, subject to the terms and conditions herein.

#### **Other Precaution**

- 1. This document may not be reprinted or reproduced, in whole or in part, without prior written consent of ROHM.
- 2. The Products may not be disassembled, converted, modified, reproduced or otherwise changed without prior written consent of ROHM.
- In no event shall you use in any way whatsoever the Products and the related technical information contained in the Products or this document for any military purposes, including but not limited to, the development of mass-destruction weapons.
- 4. The proper names of companies or products described in this document are trademarks or registered trademarks of ROHM, its affiliated companies or third parties.

Notice-PGA-E Rev.003

#### **General Precaution**

- 1. Before you use our Products, you are requested to care fully read this document and fully understand its contents. ROHM shall not be in an y way responsible or liable for failure, malfunction or accident arising from the use of a ny ROHM's Products against warning, caution or note contained in this document.
- 2. All information contained in this docume nt is current as of the issuing date and subject to change without any prior notice. Before purchasing or using ROHM's Products, please confirm the latest information with a ROHM sale s representative.
- 3. The information contained in this doc ument is provided on an "as is" basis and ROHM does not warrant that all information contained in this document is accurate an d/or error-free. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties resulting from inaccuracy or errors of or concerning such information.

**Rev.001** 

# **Mouser Electronics**

**Authorized Distributor** 

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

ROHM Semiconductor: